

PATENT ABSTRACTS OF JAPAN

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(54) MULTILAYER ELECTRONIC COMPONENT MOUNTING BOARD AND ITS MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide an electronic component mounting board wherein an interlayer interval of patterns is shortened, fine conducting hole excellent in conduction reliability can be easily formed and a connecting terminal having excellent anticorrosiveness to etching solution and connecting reliability to bonding wire is provided, and to provide a method for manufacturing such board.

SOLUTION: A mounting hole 29 is made on a core board 21 and a connecting terminal 121 is formed on the circumferential edge of the mounting hole by etching the copper foil. Then, the surface of the core board is coated with an insulating layer to form a laminated board and a connecting terminal is exposed from the insulating layer.

Then, the surface of the connecting terminal is coated with an electroless plating film 5 and heated. Surface patterns 11 and 14 are formed on the surface of the laminated board and conducting holes 31-33 are formed.

